

LITHOGRAPHIC APPARATUS AND DEVICE MANUFACTURING METHOD

FIELD

[0001] The present invention relates to a lithographic apparatus and a method for manufacturing a device.

BACKGROUND

[0002] A lithographic apparatus is a machine that applies a desired pattern onto a substrate, usually onto a target portion of the substrate. A lithographic apparatus can be used, for example, in the manufacture of integrated circuits (ICs). In that instance, a patterning device, which is alternatively referred to as a mask or a reticle, may be used to generate a circuit pattern to be formed on an individual layer of the IC. This pattern can be transferred onto a target portion (e.g. comprising part of, one, or several dies) on a substrate (e.g. a silicon wafer). Transfer of the pattern is typically via imaging onto a layer of radiation-sensitive material (resist) provided on the substrate. In general, a single substrate will contain a network of adjacent target portions that are successively patterned. Known lithographic apparatus include so-called steppers, in which each target portion is irradiated by exposing an entire pattern onto the target portion at one time, and so-called scanners, in which each target portion is irradiated by scanning the pattern through a radiation beam in a given direction (the "scanning"-direction) while synchronously scanning the substrate parallel or anti-parallel to this direction. It is also possible to transfer the pattern from the patterning device to the substrate by imprinting the pattern onto the substrate.

[0003] It has been proposed to immerse the substrate in the lithographic projection apparatus in a liquid having a relatively high refractive index, e.g. water, so as to fill a space between the final element of the projection system and the substrate. The point of this is to enable imaging of smaller features since the exposure radiation will have a shorter wavelength in the liquid. (The effect of the liquid may also be regarded as increasing the effective NA of the system and also increasing the depth of focus.) Other immersion liquids have been proposed, including water with solid particles (e.g. quartz) suspended therein.

[0004] However, submersing the substrate or substrate and substrate table in a bath of liquid (see, for example, United States patent US 4,509,852, hereby incorporated in its entirety by reference) means that there is a large body of liquid that must be accelerated during a scanning exposure. This requires additional or more powerful motors and turbulence in the liquid may lead to undesirable and unpredictable effects.

[0005] One of the solutions proposed is for a liquid supply system to provide liquid on only a localized area of the substrate and in between the final element of the projection system and the substrate (the substrate generally has a larger surface area than the final element of the projection system). One way which has been proposed to arrange for this is disclosed in PCT patent application WO 99/49504, hereby incorporated in its entirety by reference. As illustrated in Figures 2 and 3, liquid is supplied by at least one inlet IN onto the substrate, preferably along the direction of movement of the substrate relative to the final element, and is removed by at least one outlet OUT after having passed under the projection system. That is, as the substrate is scanned beneath the element in a $-X$ direction, liquid is supplied at the $+X$ side of the element and taken up at the $-X$ side. Figure 2 shows the arrangement schematically in which liquid is supplied via inlet IN and is taken up on the other side of the element by outlet OUT which is connected to a low pressure source. In the illustration of Figure 2 the liquid is supplied along the direction of movement of the substrate relative to the final element, though this does not need to be the case. Various orientations and numbers of in- and out-lets positioned around the final element are possible, one example is illustrated in Figure 3 in which four sets of an inlet with an outlet on either side are provided in a regular pattern around the final element.

[0006] In an immersion lithography technique, a space between the projection system and the substrate is filled with a liquid (such as water). During exposure of the substrate, the substrate forms part of a boundary which contains the liquid. During removal of that substrate and replacement with another substrate, for example, the liquid may be drained from the space to allow for the substrate change. A possible downside to this approach is that drying spots may be formed on an element of the projection system in contact with the liquid. Additionally or alternatively, changes in the liquid and vacuum flow to remove the liquid may take time to settle, possibly leading to loss in throughput.

SUMMARY

- [0007] Accordingly, it would be advantageous, for example, to keep an element of an immersion lithography apparatus projection system immersed during a removal of a substrate by swapping a closing plate for the substrate without disturbing the liquid which is present between the substrate and the optical element. By using another body (e.g., a closing plate) that fulfills the function of providing a boundary that contains the liquid, it may not be necessary to remove the liquid from between the substrate and the projection system during removal of the substrate (and supply of a new substrate).
- [0008] According to an aspect of the invention, there is provided a lithographic projection apparatus, comprising:
- [0009] a substrate table configured to hold a substrate;
- [00010] a projection system configured to project a patterned beam of radiation onto the substrate;
- [00011] a liquid confinement structure configured to confine a liquid in a space between the projection system and the substrate, the substrate, the substrate table, or both, configured to form a part of a boundary of the space; and
- [00012] a closing plate configured to form a part of a boundary of the space in place of the substrate, the substrate table, or both, when moved without substantially disturbing the liquid, the liquid confinement structure, or both.
- [00013] According to a further aspect of the invention, there is provided a device manufacturing method, comprising:
- [00014] providing a liquid to a space through which a patterned beam passes, a substrate, a substrate table, or both, forming a part of a boundary of the space;
- [00015] sealing the liquid to the space, the seal acting between the substrate, a substrate table, or both, and another structure;
- [00016] replacing the substrate, the substrate table, or both, with a closing plate as the part of the boundary of the space without breaking the seal; and
- [00017] projecting a patterned beam of radiation through the liquid onto the substrate.
- [00018] According to another aspect of the invention, there is provided a lithographic projection apparatus, comprising:

- [00019] a substrate table configured to hold a substrate;
- [00020] a projection system configured to project a patterned beam of radiation onto the substrate;
- [00021] a liquid confinement structure configured to confine a liquid in a space between the projection system and the substrate, the substrate, the substrate table, or both, configured to form a part of a boundary of the space;
- [00022] a closing plate displaced in a horizontal plane from the substrate table and configured to form a part of a boundary of the space in place of the substrate, the substrate table, or both; and
- [00023] an actuator configured to move the closing plate in the horizontal plane.

BRIEF DESCRIPTION OF THE DRAWINGS

- [00024] Embodiments of the invention will now be described, by way of example only, with reference to the accompanying schematic drawings in which corresponding reference symbols indicate corresponding parts, and in which:
 - [00025] Figure 1 depicts a lithographic apparatus according to an embodiment of the invention;
 - [00026] Figures 2 and 3 depict a liquid supply system for use in a lithographic projection apparatus;
 - [00027] Figure 4 depicts a further liquid supply system for use in a lithographic projection apparatus;
 - [00028] Figure 5 depicts a close up view of another liquid supply system according to an embodiment of the present invention;
 - [00029] Figures 6a and 6b show a first step in the method according to an embodiment of the present invention;
 - [00030] Figures 7a and 7b show a second step in the method according to an embodiment of the present invention;
 - [00031] Figures 8a and 8b show a third step in the method according to an embodiment of the present invention; and
 - [00032] Figures 9a and 9b show a fourth step in the method according to an

embodiment of the present invention.

DETAILED DESCRIPTION

[00033] Figure 1 schematically depicts a lithographic apparatus according to one embodiment of the invention. The apparatus comprises:

- an illumination system (illuminator) IL configured to condition a radiation beam PB (e.g. UV radiation or DUV radiation).
- a support structure (e.g. a mask table) MT constructed to hold a patterning device (e.g. a mask) MA and connected to a first positioner PM configured to accurately position the patterning device in accordance with certain parameters;
- a substrate table (e.g. a wafer table) WT constructed to hold a substrate (e.g. a resist-coated wafer) W and connected to a second positioner PW configured to accurately position the substrate in accordance with certain parameters; and
- a projection system (e.g. a refractive projection lens system) PL configured to project a pattern imparted to the radiation beam PB by patterning device MA onto a target portion C (e.g. comprising one or more dies) of the substrate W.

[00034] The illumination system may include various types of optical components, such as refractive, reflective, magnetic, electromagnetic, electrostatic or other types of optical components, or any combination thereof, for directing, shaping, or controlling radiation.

[00035] The support structure holds the patterning device in a manner that depends on the orientation of the patterning device, the design of the lithographic apparatus, and other conditions, such as for example whether or not the patterning device is held in a vacuum environment. The support structure can use mechanical, vacuum, electrostatic or other clamping techniques to hold the patterning device. The support structure may be a frame or a table, for example, which may be fixed or movable as required. The support structure may ensure that the patterning device is at a desired position, for example with respect to the projection system. Any use of the terms "reticle" or "mask" herein may be considered synonymous with the more general term "patterning device."

[00036] The term "patterning device" used herein should be broadly interpreted as referring to any device that can be used to impart a radiation beam with a pattern in its cross-

section such as to create a pattern in a target portion of the substrate. It should be noted that the pattern imparted to the radiation beam may not exactly correspond to the desired pattern in the target portion of the substrate, for example if the pattern includes phase-shifting features or so called assist features. Generally, the pattern imparted to the radiation beam will correspond to a particular functional layer in a device being created in the target portion, such as an integrated circuit.

[00037] The patterning device may be transmissive or reflective. Examples of patterning devices include masks, programmable mirror arrays, and programmable LCD panels. Masks are well known in lithography, and include mask types such as binary, alternating phase-shift, and attenuated phase-shift, as well as various hybrid mask types. An example of a programmable mirror array employs a matrix arrangement of small mirrors, each of which can be individually tilted so as to reflect an incoming radiation beam in different directions. The tilted mirrors impart a pattern in a radiation beam which is reflected by the mirror matrix.

[00038] The term "projection system" used herein should be broadly interpreted as encompassing any type of projection system, including refractive, reflective, catadioptric, magnetic, electromagnetic and electrostatic optical systems, or any combination thereof, as appropriate for the exposure radiation being used, or for other factors such as the use of an immersion liquid or the use of a vacuum. Any use of the term "projection lens" herein may be considered as synonymous with the more general term "projection system".

[00039] As here depicted, the apparatus is of a transmissive type (e.g. employing a transmissive mask). Alternatively, the apparatus may be of a reflective type (e.g. employing a programmable mirror array of a type as referred to above, or employing a reflective mask).

[00040] The lithographic apparatus may be of a type having two (dual stage) or more substrate tables (and/or two or more mask tables). In such "multiple stage" machines the additional tables may be used in parallel, or preparatory steps may be carried out on one or more tables while one or more other tables are being used for exposure.

[00041] Referring to Figure 1, the illuminator IL receives a radiation beam from a radiation source SO. The source and the lithographic apparatus may be separate entities, for example when the source is an excimer laser. In such cases, the source is not considered to form part of the lithographic apparatus and the radiation beam is passed from the source SO

to the illuminator IL with the aid of a beam delivery system BD comprising, for example, suitable directing mirrors and/or a beam expander. In other cases the source may be an integral part of the lithographic apparatus, for example when the source is a mercury lamp. The source SO and the illuminator IL, together with the beam delivery system BD if required, may be referred to as a radiation system.

[00042] The illuminator IL may comprise an adjuster AD for adjusting the angular intensity distribution of the radiation beam. Generally, at least the outer and/or inner radial extent (commonly referred to as σ -outer and σ -inner, respectively) of the intensity distribution in a pupil plane of the illuminator can be adjusted. In addition, the illuminator IL may comprise various other components, such as an integrator IN and a condenser CO. The illuminator may be used to condition the radiation beam, to have a desired uniformity and intensity distribution in its cross-section.

[00043] The radiation beam PB is incident on the patterning device (e.g., mask MA), which is held on the support structure (e.g., mask table MT), and is patterned by the patterning device. Having traversed the mask MA, the radiation beam PB passes through the projection system PL, which focuses the beam onto a target portion C of the substrate W. With the aid of the second positioner PW and position sensor IF (e.g. an interferometric device, linear encoder or capacitive sensor), the substrate table WT can be moved accurately, e.g. so as to position different target portions C in the path of the radiation beam PB. Similarly, the first positioner PM and another position sensor (which is not explicitly depicted in Figure 1) can be used to accurately position the mask MA with respect to the path of the radiation beam PB, e.g. after mechanical retrieval from a mask library, or during a scan. In general, movement of the mask table MT may be realized with the aid of a long-stroke module (coarse positioning) and a short-stroke module (fine positioning), which form part of the first positioner PM. Similarly, movement of the substrate table WT may be realized using a long-stroke module and a short-stroke module, which form part of the second positioner PW. In the case of a stepper (as opposed to a scanner) the mask table MT may be connected to a short-stroke actuator only, or may be fixed. Mask MA and substrate W may be aligned using mask alignment marks M1, M2 and substrate alignment marks P1, P2. Although the substrate alignment marks as illustrated occupy dedicated target portions, they may be located in spaces between target portions (these are known as scribe-lane alignment

marks). Similarly, in situations in which more than one die is provided on the mask MA, the mask alignment marks may be located between the dies.

[00044] The depicted apparatus could be used in at least one of the following modes:

[00045] 1. In step mode, the mask table MT and the substrate table WT are kept essentially stationary, while an entire pattern imparted to the radiation beam is projected onto a target portion C at one time (i.e. a single static exposure). The substrate table WT is then shifted in the X and/or Y direction so that a different target portion C can be exposed. In step mode, the maximum size of the exposure field limits the size of the target portion C imaged in a single static exposure.

[00046] 2. In scan mode, the mask table MT and the substrate table WT are scanned synchronously while a pattern imparted to the radiation beam is projected onto a target portion C (i.e. a single dynamic exposure). The velocity and direction of the substrate table WT relative to the mask table MT may be determined by the (de-)magnification and image reversal characteristics of the projection system PL. In scan mode, the maximum size of the exposure field limits the width (in the non-scanning direction) of the target portion in a single dynamic exposure, whereas the length of the scanning motion determines the height (in the scanning direction) of the target portion.

[00047] 3. In another mode, the mask table MT is kept essentially stationary holding a programmable patterning device, and the substrate table WT is moved or scanned while a pattern imparted to the radiation beam is projected onto a target portion C. In this mode, generally a pulsed radiation source is employed and the programmable patterning device is updated as required after each movement of the substrate table WT or in between successive radiation pulses during a scan. This mode of operation can be readily applied to maskless lithography that utilizes programmable patterning device, such as a programmable mirror array of a type as referred to above.

[00048] Combinations and/or variations on the above described modes of use or entirely different modes of use may also be employed.

[00049] A further immersion lithography solution with a localized liquid supply system is shown in Figure 4. Liquid is supplied by two groove inlets IN on either side of the projection system PL and is removed by a plurality of discrete outlets OUT arranged radially outwardly of the inlets IN. The inlets IN and OUT can be arranged in a plate with a hole in its

center and through which the projection beam is projected. Liquid is supplied by one groove inlet IN on one side of the projection system PL and removed by a plurality of discrete outlets OUT on the other side of the projection system PL, causing a flow of a thin film of liquid between the projection system PL and the substrate W. The choice of which combination of inlet IN and outlets OUT to use can depend on the direction of movement of the substrate W (the other combination of inlet IN and outlets OUT being inactive).

[00050] Another immersion lithography solution with a localized liquid supply system solution which has been proposed is to provide the liquid supply system with a liquid confinement structure which extends along at least a part of a boundary of the space between the final element of the projection system and the substrate table. Such a solution is illustrated in Figure 5. The liquid confinement structure is substantially stationary relative to the projection system in the XY plane though there may be some relative movement in the Z direction (in the direction of the optical axis). A seal is formed between the liquid confinement structure and the surface of the substrate. In an embodiment, the seal is a contactless seal such as a gas seal. Such a system with a gas seal is disclosed in United States patent application no. US 10/705,783, hereby incorporated in its entirety by reference.

[00051] Referring to Figure 5, the reservoir 10 forms a contactless seal to the substrate around the image field of the projection system so that liquid is confined to fill a space between the substrate surface and the final element of the projection system. The reservoir is formed by a liquid confinement structure 12 positioned below and surrounding the final element of the projection system PL. Liquid is brought into the space below the projection system and within the liquid confinement structure 12. The liquid confinement structure 12 extends a little above the final element of the projection system and the liquid level rises above the final element so that a buffer of liquid is provided. The liquid confinement structure 12 has an inner periphery that at the upper end preferably closely conforms to the shape of the projection system or the final element thereof and may, e.g., be round. At the bottom, the inner periphery closely conforms to the shape of the image field, e.g., rectangular though this need not be the case.

[00052] The liquid is confined in the reservoir by a seal 16 such as a gas seal between the bottom of the liquid confinement structure 12 and the surface of the substrate W. The gas seal may be formed by gas, e.g. air, synthetic air, N₂ or an inert gas, provided under pressure

via inlet 15 to the gap between liquid confinement structure 12 and substrate and extracted via first outlet 14. The overpressure on the gas inlet 15, vacuum level on the first outlet 14 and geometry of the gap are arranged so that there is a high-velocity gas flow inwards that confines the liquid. It will be understood by the person skilled in the art that other types of seal could be used to contain the liquid.

[00053] According to an embodiment of the invention, an actuated closing plate 20 is provided which moves horizontally into position under the projection system, replacing the substrate table, which moves away from its position under the projection system horizontally. The top surface of the actuated closing plate 20 is positioned at a substantially equal height to the substrate table such that continuous, undisturbed motion is allowed when the substrate table is moved away from its position under the projection system, while the seal containing the liquid in the liquid confinement structure is maintained. Part of one or more long-stroke actuators which are used to move the substrate table may also be used for horizontal actuation of the closing plate. As described in more detail below, active compensation of the change in vertical load on the substrate table, when the force associated with the liquid confinement structure 12 is moved from the substrate table to the closing plate, may also be employed. The actuated closing plate 20 is positioned and/or shaped such that it does not block any interferometer beams during measurement by these beams.

[00054] One or more advantages of supplying an actuated closing plate may include a faster substrate exchange, maintenance of gas, liquid and vacuum flows in and around the liquid confinement structure at a substantially constant level (thus possibly reducing settling times and decreasing the likelihood of contamination), reduction of mechanical disturbances of the projection system and/or the substrate table, improved utilization of space on the substrate table (as no separate closing plate need be provided on the substrate table) and elimination of drying spots on the projection system. Additionally or alternatively, the closing plate according to an embodiment of the invention may avoid the need to remove (and then replace) the liquid or moved the substrate vertically out of position so that a closing plate may be put in its place. Changes in liquid, gas and vacuum flows may take time to settle and vertical movement may cause disturbances on the projection system and on the substrate table. Turning to Figures 6 to 9, Figures 6a, 7a, 8a and 9a show plan views of the substrate table WT and actuated closing plate 20 in relation to the projection system PL. Figures 6b,

7b, 8b and 9b show side views of the substrate table WT and actuated closing plate 20 in relation to the projection system PL.

[00055] Figures 6a and 6b show the relative positions of the substrate table WT and the actuated closing plate 20 during, for example, exposure of the substrate W. The closing plate is out of the way of the projection system PL and the substrate W is lined up with the projection system PL.

[00056] Figures 7a and 7b show the relative positions of the substrate table WT and the actuated closing plate 20 when, for example, exposure of the substrate W is complete or nearly complete. The actuated closing plate 20 is moved into a position such that it is aligned horizontally with the substrate table WT and vertically with the projection system PL.

[00057] Figures 8a and 8b show the actuated closing plate 20 replacing the substrate table WT once, for example, the exposure of the substrate W is complete. Both the actuated closing plate 20 and the substrate table WT move in the same direction, at the same horizontal level.

[00058] Figures 9a and 9b show the actuated closing plate 20 in position under the projection system PL with the actuated closing plate 20 acting as one side of the boundary containing the liquid 11. The substrate W can now, for example, be swapped with another substrate W on the substrate table WT and the liquid 11 has not been disturbed.

[00059] An advantage of this system is that the liquid confinement structure 12, the projection system PL, the substrate W and/or the actuated closing plate 20 is not disturbed throughout a substrate exchange procedure. Furthermore, there may be no vertical movement of the substrate table WT and/or the actuated closing plate 20 so that the risk of gas being introduced into the liquid supply system is reduced.

[00060] Furthermore, the substrate table WT may comprise an active compensator 25 configured to compensate for a change in force when a force exerted by the liquid confinement structure is removed from it. This compensator may comprise a vertical motion sensor and/or a pressure sensor on the substrate table and a control system configured to send a compensation signal to, for example, a substrate table positioner PW, the substrate table positioner PW configured to move the substrate table WT in response to the signal to compensate for the change in force. Additionally or alternatively, the actuated closing plate 20 may also comprise an active compensator 27 in order to reduce the disturbance on the

liquid confinement structure caused, for example, when the liquid confinement structure is removed from it. This compensator may comprise a vertical motion sensor and/or a pressure sensor on the actuated closing plate 20 and a control system configured to send a compensation signal to, for example, a liquid confinement system positioner 29, the liquid confinement system positioner 29 configured to move the liquid confinement structure 12 in response to the signal to compensate for the change in force.

[00061] The substrate table WT and the actuated closing plate 20 are releasably coupleable. This means that they may be attached together when the actuated closing plate 20 is replacing the substrate table WT and vice versa; but they can be detached from each other once the replacement is complete. The actuated closing plate 20 and substrate table WT may similarly be controlled by the same system 25 or 27 or by separate systems 25 and 27. Separate long stroke actuators 22a and 22b as shown in the Figures may be used; but the separate actuators may be controlled by the same 25 or 27 or different control systems 25 and 27.

[00062] In an embodiment, forces on the actuated closing plate 20 may be measured, for example, by the actuated closing plate active compensator 27 and fed-forward to a control system (e.g., active compensator 25) of the substrate table WT so that the forces acting on the actuated closing plate 20 will be compensated for and thereby not affect the substrate table WT. In this way, the actuated closing plate 20 may work as a force measurement system for the substrate table WT.

[00063] While one or more embodiments may have been discussed in relation to removing a substrate from the substrate table and placing another substrate on the substrate table, one or more embodiments herein may be used in other applications. For example, the substrate may be kept on the substrate table but the closing plate is used simply to close the liquid confinement structure. Further, while one or more embodiments may have been discussed in terms of the substrate acting as the boundary of the space between the projection system and the substrate, the substrate table may independently or conjunction with the substrate form a part of the boundary of the space. For example, a portion of the substrate table (e.g., an alignment mark) may be positioned under the liquid confinement structure and form a part of the boundary of the space. Accordingly, the closing plate may replace the substrate table as a part of the boundary of the space, or vice versa.

[00064] In European Patent Application No. 03257072.3, the idea of a twin or dual stage immersion lithography apparatus is disclosed. Such an apparatus is provided with two tables for supporting a substrate. Leveling measurements are carried out with a table at a first position, without immersion liquid, and exposure is carried out with a table at a second position, where immersion liquid is present. Alternatively, the apparatus has only one table

[00065] Although specific reference may be made in this text to the use of lithographic apparatus in the manufacture of ICs, it should be understood that the lithographic apparatus described herein may have other applications, such as the manufacture of integrated optical systems, guidance and detection patterns for magnetic domain memories, flat-panel displays, liquid-crystal displays (LCDs), thin-film magnetic heads, etc. The skilled artisan will appreciate that, in the context of such alternative applications, any use of the terms "wafer" or "die" herein may be considered as synonymous with the more general terms "substrate" or "target portion", respectively. The substrate referred to herein may be processed, before or after exposure, in for example a track (a tool that typically applies a layer of resist to a substrate and develops the exposed resist), a metrology tool and/or an inspection tool. Where applicable, the disclosure herein may be applied to such and other substrate processing tools. Further, the substrate may be processed more than once, for example in order to create a multi-layer IC, so that the term substrate used herein may also refer to a substrate that already contains multiple processed layers.

[00066] The terms "radiation" and "beam" used herein encompass all types of electromagnetic radiation, including ultraviolet (UV) radiation (e.g. having a wavelength of or about 365, 248, 193, 157 or 126 nm).

[00067] The term "lens", where the context allows, may refer to any one or combination of various types of optical components, including refractive and reflective optical components.

[00068] While specific embodiments of the invention have been described above, it will be appreciated that the invention may be practiced otherwise than as described. For example, the invention may take the form of a computer program containing one or more sequences of machine-readable instructions describing a method as disclosed above, or a data storage medium (e.g. semiconductor memory, magnetic or optical disk) having such a computer program stored therein.

[00069] One or more embodiments of the present invention may be applied to any immersion lithography apparatus, in particular, but not exclusively, to those types mentioned above. A liquid supply system as contemplated herein should be broadly construed. In certain embodiments, it may be a mechanism or combination of structures that provides a liquid to a space between the projection system and the substrate and/or substrate table. It may comprise a combination of one or more structures, one or more liquid inlets, one or more gas inlets, one or more gas outlets, and/or one or more liquid outlets that provide liquid to the space. In an embodiment, a surface of the space may be a portion of the substrate and/or substrate table, or a surface of the space may completely cover a surface of the substrate and/or substrate table, or the space may envelop the substrate and/or substrate table. The liquid supply system may optionally further include one or more elements to control the position, quantity, quality, shape, flow rate or any other features of the liquid.

[00070] The descriptions above are intended to be illustrative, not limiting. Thus, it will be apparent to one skilled in the art that modifications may be made to the invention as described without departing from the scope of the claims set out below.

CLAIMS

1. A lithographic projection apparatus, comprising:
 - a substrate table configured to hold a substrate;
 - a projection system configured to project a patterned beam of radiation onto the substrate;
 - a liquid confinement structure configured to confine a liquid in a space between the projection system and the substrate, the substrate, the substrate table, or both, configured to form a part of a boundary of the space;
 - an actuated closing plate configured to form a part of a boundary of the space in place of the substrate, the substrate table, or both, when moved without substantially disturbing the liquid, the liquid confinement structure, or both;
 - wherein the an actuated closing plate and the substrate table are configured to move horizontally relative to each other when the actuated closing plate forms part of the boundary of the space.
2. The apparatus of claim 1, where in the actuated closing plate is configured to moves horizontally into position under the projection system, to replace the substrate table, which moves away from its position under the projection system horizontally.
3. The apparatus of claim 2, wherein the actuated closing plate is configured to be positioned alongside the substrate table when it replaces the substrate table.
4. The apparatus of claim 1, wherein there is no vertical movement of the substrate table and/or the actuated closing plate when the closing plate forms part of the boundary of the space.
5. The apparatus according to claim 1, comprising an actuator configured to move the closing plate along a horizontal plane to form the part of the boundary of the space in place of the substrate, the substrate table, or both.
6. The apparatus according to claim 1, comprising an actuator configured to move the

closing plate in a same plane as the substrate, the substrate table, or both, and to follow the substrate, the substrate table, or both, across the liquid confinement structure.

7. The apparatus of claim 1, where in at least one of the substrate table and the closing plate comprises an active compensator for compensating for a change in force exerted by the liquid confinement structure when it is introduced to or removed from the respective substrate, substrate table or closing plate.
8. The apparatus according to claim 1, wherein the active compensator is configured to compensate for a change in load on the substrate table in a direction perpendicular to a direction of movement of the substrate table due to the replacement of the substrate, the substrate table, or both, with the closing plate as a part of the boundary of the space.
9. The apparatus according to claim 1, wherein the substrate table and the closing plate are releasably coupleable.
10. The apparatus according to claim 9, wherein the substrate table and the closing plate are configured to couple together when the actuated closing plate is replacing the substrate table WT and/or the substrate table is replacing the actuated closing plate.
11. The apparatus according to claim 10, wherein the substrate table and the closing place are configured to detach from each other after replacement.
12. The apparatus according to claim 1, comprising a first actuator configured to move the closing plate and a separate second actuator configured to move the substrate table.
13. The apparatus according to claim 1, wherein the closing plate is at a same vertical level as the substrate table and neither the closing plate nor the substrate table is moved out of the vertical level to replace the substrate, the substrate table, or both, with the closing plate as a part of the boundary of the space, to replace the closing plate with the substrate, the substrate table, or both as a part of the boundary of the space, or both.

14. The apparatus according to claim 1, wherein the liquid supply system is configured to constantly circulate the liquid in a flow pattern and the flow pattern is not disturbed by the replacement of the closing plate with the substrate, the substrate table, or both as a part of the boundary of the space, replacement of the substrate, the substrate table, or both with the closing plate as a part of the boundary of the space, or both.
15. A device manufacturing method, comprising:
providing a liquid to a space through which a patterned beam passes, a substrate, a substrate table, or both, forming a part of a boundary of the space;
sealing the liquid to the space, the seal acting between the substrate, a substrate table, or both, and another structure;
replacing the substrate, the substrate table, or both, with an actuated closing plate as the part of the boundary of the space without breaking the seal;
projecting a patterned beam of radiation through the liquid onto the substrate; and
moving the actuated closing plate and the substrate table horizontally relative to each other as the actuated closing plate forms part of the boundary of the space.
16. The method according to claim 15, comprising moving the closing plate along a horizontal plane to form the part of the boundary of the space in place of the substrate, the substrate table, or both.
17. The method according to claim 15, comprising moving the closing plate in a same plane as the substrate, the substrate table, or both, and to follow the substrate, the substrate table, or both.
18. The method of claim 15 comprising actively compensating for a change in force on a substrate table or closing plate when a force exerted on said substrate or closing plate is removed from it.
19. The method according to claim 18, wherein the compensating for a change in load on the substrate table is in a direction perpendicular to a direction of movement of the substrate table due to the replacement of the substrate, the substrate table, or both, with the closing plate

as a part of the boundary of the space.

20. The method according to claim 18, comprising compensating for a change in load on a liquid confinement structure, used to at least partly confine the liquid in the space, in a direction perpendicular to a direction of movement of the substrate table due to replacement of the closing plate with the substrate, the substrate table, or both, as a part of the boundary of the space.

21. The method according to claim 15, comprising releasably coupling the substrate table and the closing plate.

22. The method according to claim 15, comprising separately moving the closing plate and the substrate table.

23. The method according to claim 15, wherein the closing plate is at a same vertical level as the substrate table and neither the closing plate nor the substrate table is moved out of the vertical level to replace the substrate, the substrate table, or both, with the closing plate as a part of the boundary of the space, to replace the closing plate with the substrate, the substrate table, or both as a part of the boundary of the space, or both.

23. The method according to claim 15, wherein the liquid is constantly circulated in a flow pattern and the flow pattern is not disturbed by the replacement of the closing plate with the substrate, the substrate table, or both as a part of the boundary of the space, replacement of the substrate, the substrate table, or both with the closing plate as a part of the boundary of the space, or both.

24. A lithographic projection apparatus, comprising:

a substrate table configured to hold a substrate;

a projection system configured to project a patterned beam of radiation onto the substrate;

a liquid confinement structure configured to confine a liquid in a space between the projection system and the substrate, the substrate, the substrate table, or both, configured to

form a part of a boundary of the space;

a closing plate displaced in a horizontal plane from the substrate table and configured to form a part of a boundary of the space in place of the substrate, the substrate table, or both;

an actuator configured to move the closing plate in the horizontal plane;

wherein the substrate table is configured to move horizontally relative to the closing plate when the actuated closing plate forms part of the boundary of the space.

25. The apparatus according to claim 24, wherein the actuator is configured to move the closing plate in a same plane as the substrate, the substrate table, or both, and to follow the substrate, the substrate table, or both, across the liquid confinement structure.

26. The apparatus of claim 24, wherein at least one of the substrate table and the closing plate comprises an active compensator for compensating for a change in force exerted by the liquid confinement structure when it is introduced to or removed from the respective substrate, substrate table or closing plate.

27. The apparatus according to claim 26, wherein the active compensator is configured to compensate for a change in load on the substrate table in a direction perpendicular to a direction of movement of the substrate table due to the replacement of the substrate, the substrate table, or both, with the closing plate as a part of the boundary of the space.

28. The apparatus according to claim 24, wherein the substrate table and the closing plate are releasably coupleable.

29. The apparatus according to claim 24, comprising a separate actuator configured to move the substrate table.

30. The apparatus according to claim 29, comprising a controller configured to separately control the closing plate and the substrate table.

31. The apparatus according to claim 24, wherein the actuator is configured to move both the closing plate and the substrate table.

32. The apparatus according to claim 24, wherein the closing plate is at a same vertical level as the substrate table and neither the closing plate nor the substrate table is moved out of the vertical level to replace the substrate, the substrate table, or both, with the closing plate as a part of the boundary of the space, to replace the closing plate with the substrate, the substrate table, or both as a part of the boundary of the space, or both.

33. The apparatus according to claim 24, wherein the actuator comprises a long stroke actuator and comprises a long stroke actuator configured to move the substrate table.

34. The apparatus according to claim 24, wherein the liquid supply system is configured to constantly circulate the liquid in a flow pattern and the flow pattern is not disturbed by the replacement of the closing plate with the substrate, the substrate table, or both as a part of the boundary of the space, replacement of the substrate, the substrate table, or both with the closing plate as a part of the boundary of the space, or both.